



## Product Change Notification: DSNO-17TVWI575

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**Date:**

24-Feb-2025

**Product Category:**

8-Bit Microcontrollers, Interface- Infrared Products, KEELOQ® Encoder Devices

**Notification Subject:**

CCB 7364.006 Initial Notice: Qualification of Microchip Technology Gresham – Fab 4 (GRTM) as a new fabrication location for selected HCS370, MCP2150, MCP2155, PIC16F627, PIC16F628, PIC16F84A, PIC16F870, PIC16F871, PIC16F872, PIC16F873, PIC16F874, PIC16F876 and PIC16F877 device families available in various packages.

**Affected CPNs:**

[DSNO-17TVWI575\\_Affected\\_CPN\\_02242025.pdf](#)  
[DSNO-17TVWI575\\_Affected\\_CPN\\_02242025.csv](#)

**PCN Status:** Initial Notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the files found in the Affected CPNs section.  
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

**Description of Change:** Qualification of Microchip Technology Gresham – Fab 4 (GRTM) as a new fabrication location for selected HCS370, MCP2150, MCP2155, PIC16F627, PIC16F628, PIC16F84A, PIC16F870, PIC16F871, PIC16F872, PIC16F873, PIC16F874, PIC16F876 and PIC16F877 device families available in various packages.

**Pre and Post Summary Changes:**

	Pre Change	Post Change
<b>Fabrication Site</b>	Microchip Technology Tempe – Fab 2 (TMGR)	Microchip Technology Gresham – Fab 4 (GRTM)

<b>Wafer Size</b>	8"	8"
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**Impacts to Datasheet:** None

**Change Impact:** None

**Reason for Change:** To improve manufacturability and on time delivery performance by qualifying a new fabrication location (GRTM - FAB 4), which is a Microchip-owned facility that offers significant expansion potential to better meet future client demand. \*Note: The attached file called Tempe\_Fab2\_IATF\_Decertification is for the manufacturing site deactivation of Microchip Technology Tempe – Fab 2 (TMGR), contact your local Microchip sales office for inquiries.

**Change Implementation Status:** In Progress

**Estimated Qualification Completion Date:** October 2025

**Note:** Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

**Timetable Summary:**

	February 2025					>	October 2025				
Work Week	05	06	07	08	09		40	41	42	43	44
<b>Initial PCN Issue Date</b>					X						
<b>Qual Report Availability</b>								X			
<b>Final PCN Issue Date</b>								X			

**Method to Identify Change:** Traceability Code

**Qualification Plan:** Please open the attachments included with this PCN labeled as PCN\_#\_Qual\_Plan.

**Revision History:** February 24, 2025: Issued initial notification.

**Note:** The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

**Attachments:**

**Tempe\_Fab2\_IATF\_Decertification.pdf**  
**PCN\_DSNO-17TVWI575\_Qualification-Plan.pdf**

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

**Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

PIC16F876-04/SO

PIC16F876-20/SO

PIC16LF876-04/SO

PIC16F876-04I/SO

PIC16F876-20I/SO

PIC16LF876-04I/SO

PIC16F876T-20/SO

PIC16LF876T-04/SO

PIC16F876T-20I/SO

PIC16F873-04/SO

PIC16F873-20/SO

PIC16LF873-04/SO

PIC16F873-04I/SO

PIC16F873-20I/SO

PIC16LF873-04I/SO

PIC16F873T-04/SO

PIC16F873T-20/SO

PIC16F873T-04I/SOVAO

PIC16F873T-20I/SO

PIC16LF873T-04I/SO

PIC16F628-04/SS

PIC16F628-20/SS

PIC16LF628-04/SS

PIC16F628-04E/SS

PIC16F628-20E/SS

MCP2150-I/SSRVB

MCP2155-I/SSRVB

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MCP2150-I/SS

MCP2155-I/SS

PIC16F628-04I/SS

PIC16F628-20I/SS

PIC16LF628-04I/SS

MCP2150-I/SSRVC

MCP2155-I/SSRVC

PIC16F628T-04/SS

PIC16F628T-20/SS

MCP2150T-I/SSRVB

MCP2155T-I/SSRVB

MCP2150T-I/SS

MCP2155T-I/SS

PIC16LF628T-04I/SS

MCP2150T-I/SSRVC

MCP2155T-I/SSRVC

PIC16F870-E/SS

PIC16F870-I/SS

PIC16LF870-I/SS

PIC16F870T-I/SS

PIC16LF870T-I/SS

PIC16F870T-E/SS

PIC16F84A-04/SS

PIC16F84A-20/SS

PIC16LF84A-04/SS

PIC16F84A-04I/SS

PIC16F84A-20I/SS

PIC16LF84A-04I/SS

PIC16F84AT-20/SS

PIC16F628-04I/P043

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PIC16F876-04/SP

PIC16F876-20/SP

PIC16LF876-04/SP

PIC16F876-04I/SP

PIC16F876-20I/SP

PIC16F876-04E/SOVAO

PIC16LF627-04/SS

PIC16F627-04I/SS

PIC16F627-20I/SS

PIC16LF627-04I/SS

PIC16F627T-20I/SS

PIC16F871-I/PT

PIC16LF871-I/PT

PIC16F877-04/PT

PIC16F877-20/PT

PIC16LF877-04/PT

PIC16F871-I/P

PIC16LF871-I/P

HCS370-I/SL

PIC16F84A-04/P

PIC16F84A-20/P

PIC16LF84A-04/P

PIC16F84A-04E/P

PIC16F84A-20E/P

PIC16F84A-04I/P

PIC16F84A-20I/P

PIC16LF84A-04I/P

PIC16F627-04/P

PIC16F627-20/P

PIC16LF627-04/P

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PIC16F627-04I/P

PIC16F627-20I/P

PIC16LF627-04I/P

PIC16F628-04/P

PIC16F876-20I/SOVAO

PIC16F628-04/SO

PIC16F628-20/SO

PIC16LF628-04/SO

PIC16F628-04E/SO

PIC16F628-20E/SO

MCP2150-I/SORVB

MCP2155-I/SORVB

MCP2150-I/SO

MCP2155-I/SO

PIC16F628-04I/SO

PIC16F628-20I/SO

PIC16LF628-04I/SO

MCP2150-I/SORVC

MCP2155-I/SORVC

PIC16F628T-04/SO

PIC16LF628T-04/SO

MCP2150T-I/SORVB

MCP2155T-I/SORVB

MCP2150T-I/SO

MCP2155T-I/SO

PIC16F628T-04I/SO

PIC16F628T-20I/SO

MCP2150T-I/SORVC

MCP2155T-I/SORVC

PIC16F870-E/SP

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PIC16F870-I/SP

PIC16LF870-I/SP

PIC16F877-04/P

PIC16F877-20/P

PIC16LF877-04/P

PIC16F877-04E/P

PIC16F877-10E/P

PIC16F877-04I/P

PIC16F877-20I/P

PIC16LF877-04I/P

PIC16F874-04/PQ

PIC16F874-20/PQ

PIC16F874-04I/PQ

PIC16F874-20I/PQ

PIC16LF874-04I/PQ

PIC16F877-04/PQ

PIC16F877-20/PQ

PIC16LF877-04/PQ

PIC16F877-10E/PQ

PIC16F877-04I/PQ

PIC16F877-20I/PQ

PIC16LF877-04I/PQ

PIC16F627-04/SO

PIC16F627-20/SO

PIC16LF627-04/SO

PIC16F627-04E/SO

PIC16F627-20E/SO

PIC16F627-04I/SO

PIC16F627-20I/SO

PIC16LF627-04I/SO

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PIC16F627T-04I/SO

PIC16F84A-04/SO

PIC16F84A-20/SO

PIC16LF84A-04/SO

PIC16F84A-04I/SO

PIC16F84A-20I/SO

PIC16F877-04E/PT

PIC16F877-10E/PT

PIC16F877-04I/PT

PIC16F877-20I/PT

PIC16LF877-04I/PT

PIC16F877T-20I/PT

MCP2150-I/SSGRVB

MCP2150T-I/SSGRVB

MCP2155T-I/SSG

MCP2150T-I/SSRVCG

MCP2155T-I/SSRVCG

PIC16F874-04/P

PIC16F874-20/P

PIC16LF874-04/P

PIC16F874-04I/P

PIC16F874-20I/P

PIC16LF84A-04I/SO

PIC16F84AT-04/SO

PIC16F84AT-20/SO

PIC16F84AT-04I/SO

PIC16LF84AT-04I/SO

PIC16F872-E/SOVAO

PIC16F872-I/SOVAO

PIC16F872T-E/SOVAO

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PIC16LF84AT-04I/SSVAO

PIC16F628-20E/SSVAO

PIC16LF84AT-04I/SOVAO

PIC16F873-20/SOV01

PIC16F873T-20/SOV01

PIC16F874-04/PT

PIC16F874-20I/PT

PIC16F873-04/SO041

PIC16F872T-I/SS034

PIC16F628-20/P

PIC16F628-04E/P

MCP2150-I/PRVB

MCP2155-I/PRVB

MCP2150-I/P

MCP2155-I/P

PIC16F628-04I/P

PIC16F628-20I/P

PIC16LF628-04I/P

MCP2150-I/PRVC

MCP2155-I/PRVC

PIC16F871-I/L

PIC16LF871-I/L

PIC16F871T-I/L

PIC16F872-E/SP

PIC16F872-I/SP

PIC16LF872-I/SP

PIC16F873-04/SP

PIC16F873-20/SP

PIC16LF873-04/SP

PIC16F873-04I/SP

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PIC16F873-20I/SP

PIC16F877-04/L

PIC16F877-20/L

PIC16LF877-04/L

PIC16F877-04I/L

PIC16F877-20I/L

PIC16LF877-04I/L

PIC16F877T-04/L

PIC16F877T-20/L

PIC16F877T-20I/L

PIC16F874-04/L

PIC16F874-20/L

PIC16F874-04I/L

PIC16F874-20I/L

PIC16LF874-04I/L

PIC16LF874T-04I/L

PIC16F870-E/SO

PIC16F870-I/SO

PIC16LF870-I/SO

PIC16F870T-I/SO

PIC16LF870T-I/SO

PIC16F872-E/SO

PIC16F872-I/SO

PIC16LF872-I/SO

PIC16F872T-I/SO

PIC16LF872T-I/SO

PIC16F872-E/SS

PIC16F872-I/SS

PIC16LF872-I/SS

PIC16F872T-I/SS

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PIC16LF872T-I/SS

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